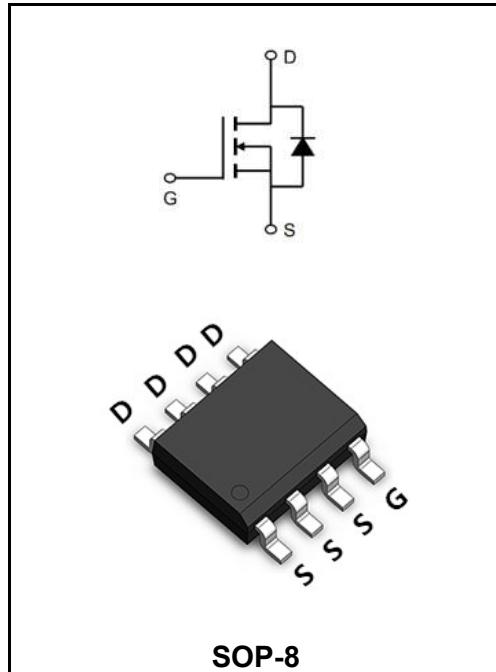


**40V N-CHANNEL ENHANCEMENT MODE MOSFET**
**MAIN CHARACTERISTICS**

$I_D$	25A
$V_{DSS}$	40V
$R_{DS(on)-typ}(@V_{GS}=10V)$	< 7mΩ (Type: 5.5 mΩ)


**Application**

- Battery protection
- Load switch
- Uninterruptible power supply

**Maximum Ratings at  $T_c=25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbols	Value	Units
Drain-Source Voltage	$V_{DS}$	40	V
Gate - Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, $V_{GS} @ 10V^1$ @ $T_A=25^\circ\text{C}$	$I_D$	25.5	A
Continuous Drain Current, $V_{GS} @ 10V^1$ @ $T_A=70^\circ\text{C}$	$I_D$	18.4	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	75	A
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	176	mJ
Avalanche Current	$I_{AS}$	39	A
Total Power Dissipation <sup>4</sup> @ $T_A=25^\circ\text{C}$	$P_D$	1.5	W
Storage Temperature Range	$T_{STG}$	-55 to +150	°C
Operating Junction Temperature Range	$T_J$	-55 to +150	°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	85	°C/W
Thermal Resistance Junction-Case <sup>1</sup>	$R_{\theta JC}$	28	°C/W

**Maximum Ratings at T<sub>c</sub>=25°C unless otherwise specified**

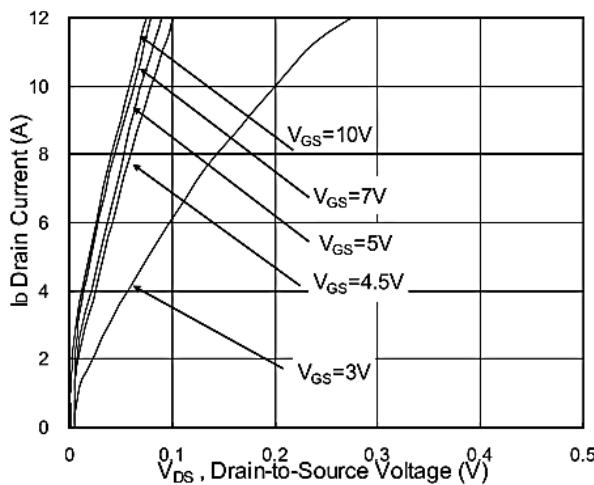
Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	BV <sub>DSS</sub>	40	44	-	V
BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA	ΔBV <sub>DSS/ΔTJ</sub>	-	0.034	-	V/°C
Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =10A	R <sub>DS(ON)</sub>	-	5.5	7.5	mΩ
	V <sub>GS</sub> =4.5V, I <sub>D</sub> =8A		-	6.5	10	
Gate -Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	V <sub>GS(th)</sub>	1.0	1.6	2.5	V
V <sub>GS(th)</sub> Temperature Coefficient		ΔV <sub>GS(th)</sub>	-	-4.96	-	mV/°C
Drain -Source Leakage Current	V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	I <sub>DSS</sub>	-	-	1	μA
	V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C		-	-	5	
Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	I <sub>GSS</sub>	-	-	±100	nA
Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =10A	g <sub>FS</sub>	-	40	-	S
Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	R <sub>g</sub>	-	1.6	-	
Total Gate Charge(4.5V)	V <sub>DS</sub> =20V V <sub>GS</sub> =4.5V I <sub>D</sub> =10A	Q <sub>g</sub>	-	18.8	-	nC
Gate-Source Charge		Q <sub>gs</sub>	-	4.7	-	
Gate-Drain Charge		Q <sub>gd</sub>	-	8.2	-	
Turn-on delay time	V <sub>DD</sub> =15V V <sub>GS</sub> =10V R <sub>G</sub> =3.3Ω I <sub>D</sub> =1A	t <sub>d(on)</sub>	-	14.3	-	ns
Rise Time		T <sub>r</sub>	-	2.6	-	
Turn-Off Delay Time		t <sub>d(OFF)</sub>	-	77	-	
Fall Time		t <sub>f</sub>	-	4.8	-	
Input Capacitance	V <sub>DS</sub> =15V V <sub>GS</sub> =0V f=1.0MHz	C <sub>iss</sub>	-	2332	-	pF
Output Capacitance		C <sub>oss</sub>	-	193	-	
Reverse Transfer Capacitance		C <sub>rss</sub>	-	138	-	
Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	I <sub>s</sub>	-	-	10.5	A
Pulsed Source Current <sup>2,5</sup>		I <sub>SM</sub>	-	-	42	A
Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>s</sub> =1A , T <sub>J</sub> =25°C	V <sub>SD</sub>	-	-	1	V

Note :

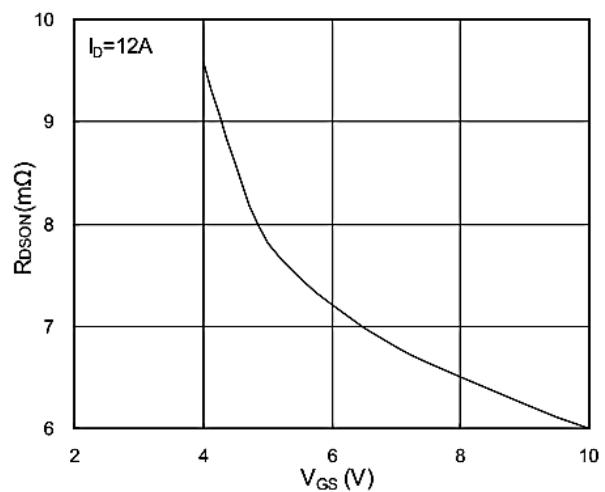
1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
3. The power dissipation is limited by 175°C junction temperature
4. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

**Ratings and Characteristic Curves**

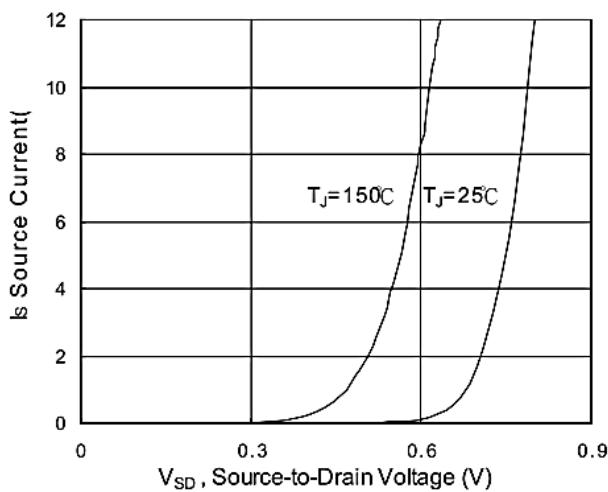
**Typical Characteristics**



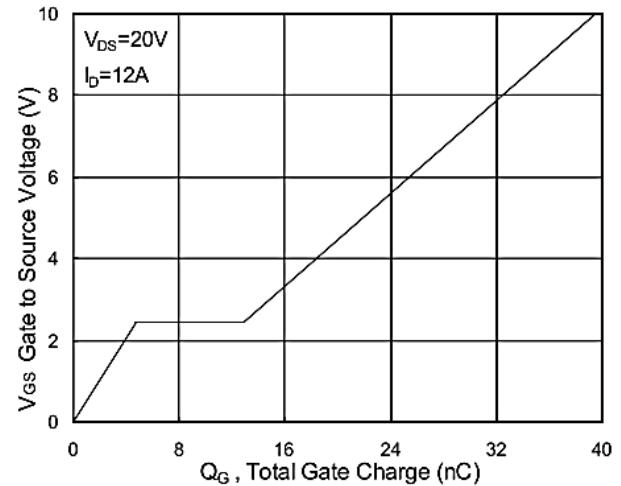
**Fig.1 Typical Output Characteristics**



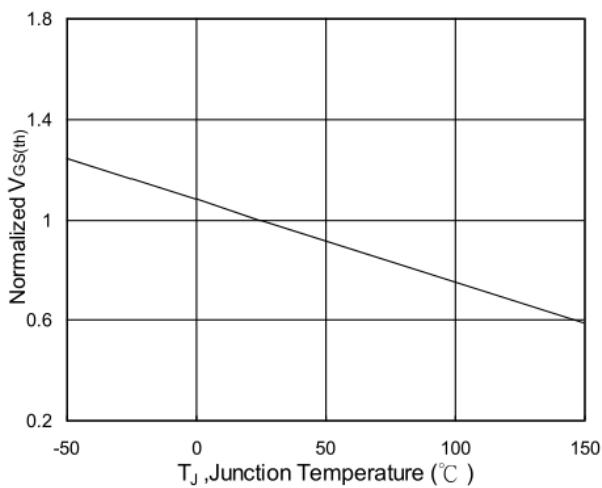
**Fig.2 On-Resistance vs. G-S Voltage**



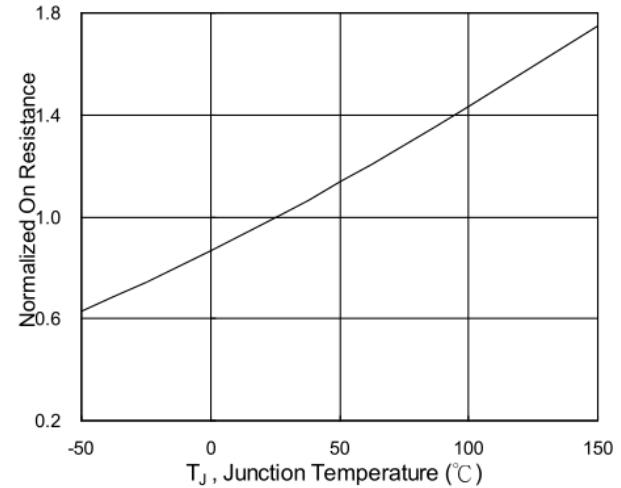
**Fig.3 Forward Characteristics of Reverse**



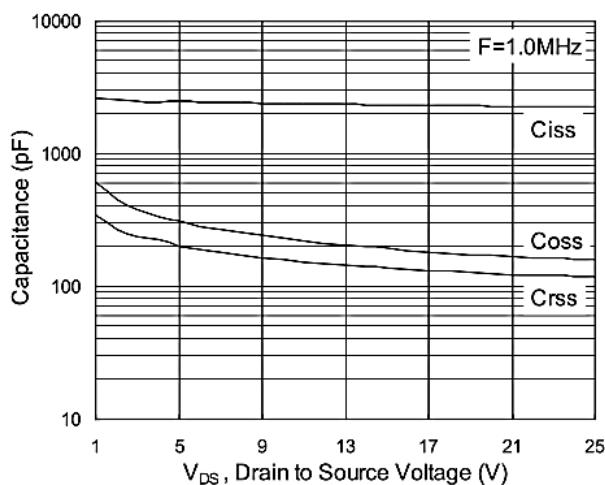
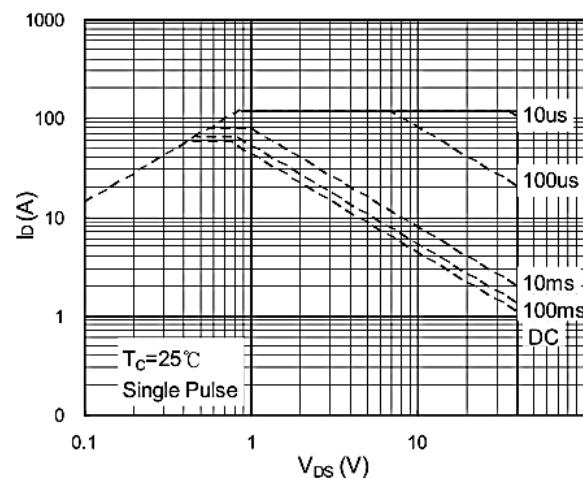
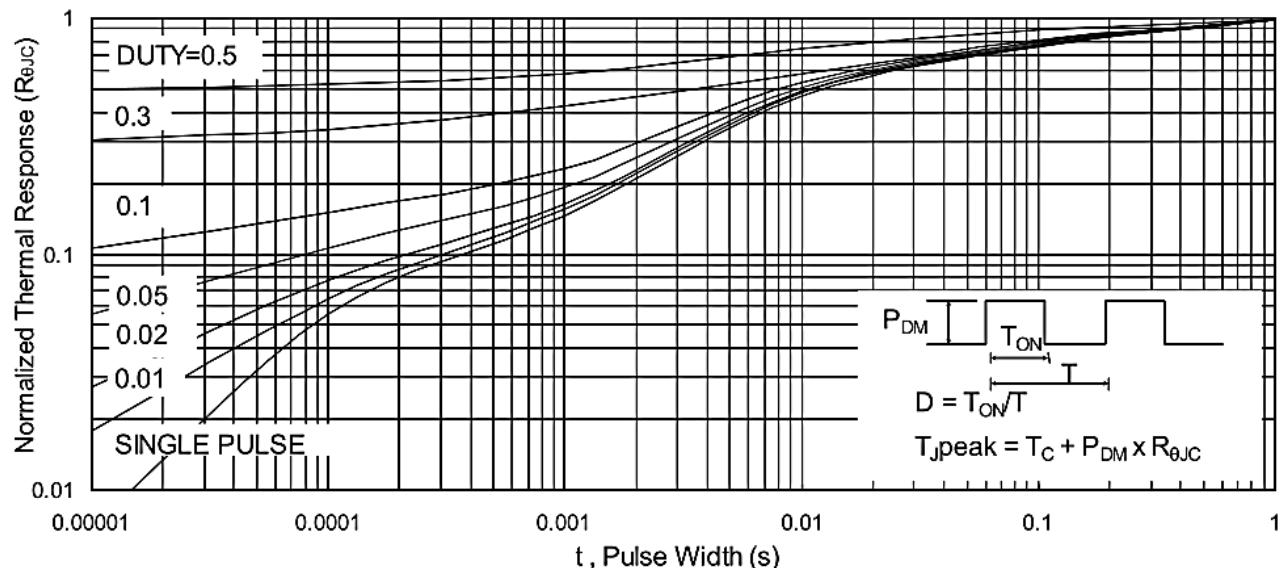
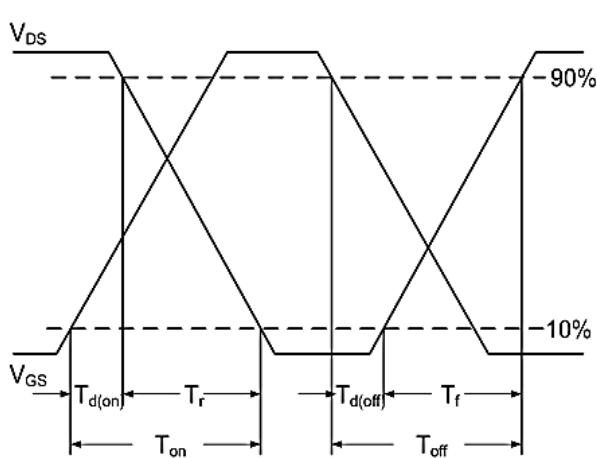
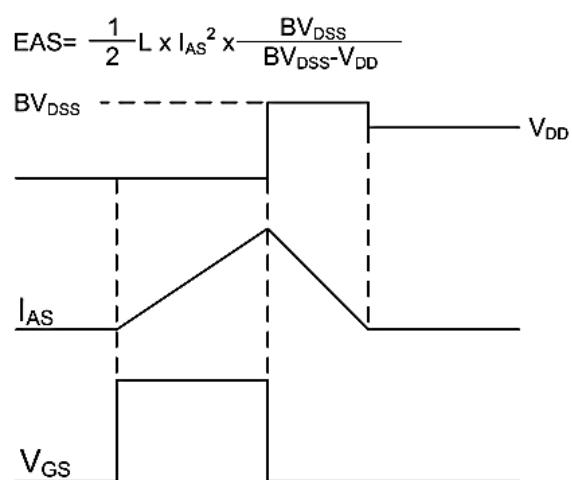
**Fig.4 Gate-Charge Characteristics**



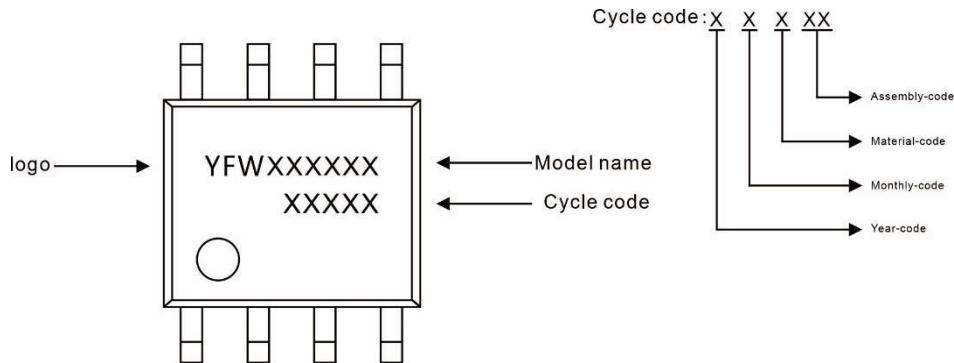
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**

**Ratings and Characteristic Curves**

**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Waveform**

### Marking Diagram

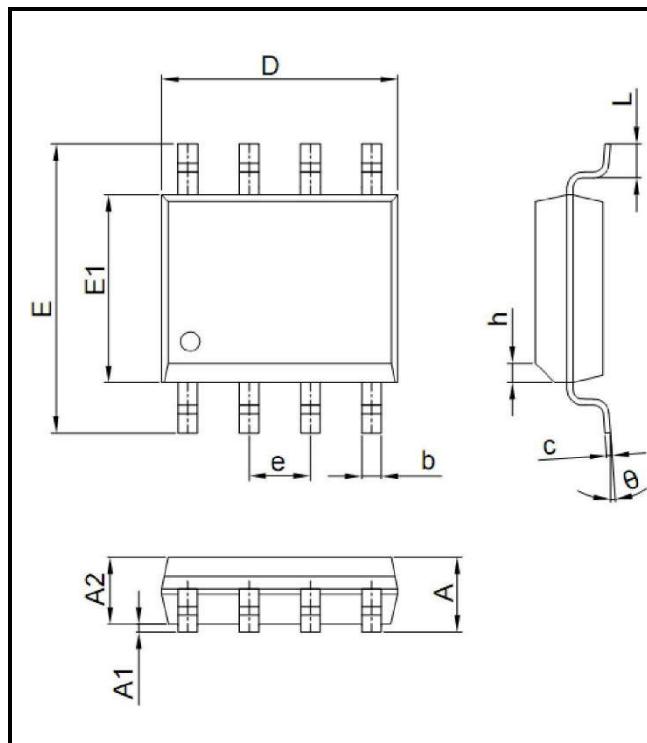


### Ordering information

Package	Packing Description	Packing Quantity
SOP-8	Tape/Reel,13"reel	3000PCS/Reel 30000PCS/Carton

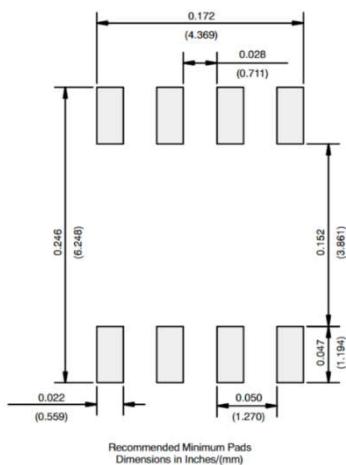
### Package Dimensions

#### SOP-8



Dim	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
A2	1.35	1.50	0.053	0.059
b	0.35	0.55	0.014	0.022
c	0.15	0.25	0.006	0.010
D	4.80	5.00	0.189	0.197
D1	3.10	3.50	0.122	0.138
E	5.80	6.20	0.228	0.244
E1	3.80	4.00	0.150	0.157
E2	2.20	2.60	0.087	0.102
e	1.27 (BSC)		0.050 (BSC)	
L	0.40	1.27	0.016	0.050
θ	0°	8°	0°	8°

### The recommended mounting pad size



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